

Jinwook Song

List of Publications by Year in descending order

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papers

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citations

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301
citing authors

#	ARTICLE	IF	CITATIONS
1	Channel Characteristic-Based Deep Neural Network Models for Accurate Eye Diagram Estimation in High Bandwidth Memory (HBM) Silicon Interposer. IEEE Transactions on Electromagnetic Compatibility, 2022, 64, 196-208.	2.2	11
2	A Near Field Analytical Model for EMI Reduction and Efficiency Enhancement Using an <i>n</i> -th Harmonic Frequency Shielding Coil in a Loosely Coupled Automotive WPT System. IEEE Transactions on Electromagnetic Compatibility, 2021, 63, 935-946.	2.2	15
3	Optimal Power Distribution Network Design for High-Performance Solid-State-Drive Based on Novel Target-Impedance Extraction Method. , 2021, , .		2
4	Crosstalk-included PAM-4 Worst Eye Diagram Estimation Method for High-speed Serial Links. , 2021, , .		0
5	PAM-4 based PCIe 6.0 Channel Design Optimization Method using Bayesian Optimization. , 2021, , .		3
6	Smartwatch Strap Wireless Power Transfer System With Flexible PCB Coil and Shielding Material. IEEE Transactions on Industrial Electronics, 2019, 66, 4054-4064.	7.9	62
7	Signal Integrity Design and Analysis of Differential High-Speed Serial Links in Silicon Interposer With Through-Silicon Via. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 107-121.	2.5	26
8	Low Leakage Electromagnetic Field Level and High Efficiency Using a Novel Hybrid Loop-Array Design for Wireless High Power Transfer System. IEEE Transactions on Industrial Electronics, 2019, 66, 4356-4367.	7.9	26
9	Design and Measurement of a Novel On-Interposer Active Power Distribution Network for Efficient Simultaneous Switching Noise Suppression in 2.5-D/3-D IC. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 317-328.	2.5	12
10	A Frequency-Selective EMI Reduction Method for Tightly Coupled Wireless Power Transfer Systems Using Resonant Frequency Control of a Shielding Coil in Smartphone Application. IEEE Transactions on Electromagnetic Compatibility, 2019, 61, 2031-2039.	2.2	18
11	Signal Integrity Design and Analysis of Silicon Interposer for GPU-Memory Channels in High-Bandwidth Memory Interface. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 1658-1671.	2.5	40
12	Design, Simulation and Measurement of Flexible PCB Coils for Wearable Device Wireless Power Transfer. , 2018, , .		9
13	Core-Shared-Repeater (CSR) Coil Scheme for Low EMI and Efficient WPT System in Ultra-Thin Digital TV. , 2018, , .		2
14	Modeling, Measurement, and Analysis of Audio Frequency Ground Integrity for a TDMA Smartphone System. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 519-530.	2.5	4
15	Design and analysis of wireless power transfer system using flexible coil and shielding material on smartwatch strap. , 2017, , .		15
16	Chip-level wireless power transfer scheme design for next generation wireless interconnected three-dimensional integrated circuits. , 2017, , .		1
17	analysis of power inverter parasitic inductances effect on switching characteristics for accurate electromagnetic interference (EMI) estimation. , 2017, , .		3
18	Hybrid metamaterial with zero and negative permeability to enhance efficiency in wireless power transfer system. , 2016, , .		12

#	ARTICLE	IF	CITATIONS
19	Probe Card Design with Signal and Power Integrity for Wafer-Level Application Processor Test in LPDDR Channel. , 2016, , .		2
20	Electromagnetic Bandgap Design for Power Distribution Network Noise Isolation in the Glass Interposer. , 2016, , .		2
21	Multi-layer probe card design with signal/power integrity for wafer-level AP test in LPDDR4 channel. , 2016, , .		1
22	PCB-package to chip wireless power transfer scheme using magnetic-field resonance coupling for high-density 3-D IC. , 2016, , .		4
23	Active Silicon Interposer Design for Interposer-Level Wireless Power Transfer Technology for High-Density 2.5-D and 3-D ICs. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, , 1-14.	2.5	13
24	Design of an on-interposer passive equalizer embedded on a ground plane for 30Gbps serial data transmission. , 2015, , .		1
25	Analysis of high frequency characteristics of power inverter using accurate IGBT model based on datasheet and measurement. , 2015, , .		3
26	Modeling and analysis of return paths of common mode EMI noise currents from motor drive system in hybrid electric vehicle. , 2015, , .		9
27	Analysis of Wireless Power Transfer system design on active silicon interposer for low voltage applications in 3D-IC. , 2014, , .		0
28	Design and analysis of magnetically coupled coil structures for PCB-to-active interposer wireless power transfer in 2.5D/3D-IC. , 2014, , .		5